Dear All

From: Marek Idzik

Subject: Re: 41th FCAL Hardware WG Meeting

Date: Wed, 22 May 2019 18:36:36

Short summary from the 41th Hardware WG FCAL Meeting:  
  
Jakub gave the status of FPGA-base FLAME readout  
- FLAME should be available at the beginning of June  
- due to bad reticle arrangement we will get only ~20 FLAME chips,

which is enough for test but not for beam-test  
- there will be 3 wafers left (~100 FLAMEs per wafer), so in case the   
FLAME is working well, we will request for special dicing to get enough chips  
- PCB for FLAME tests were designed and sent to production  
- PCB for beam-test (for 8 FLAME chips) has not been yet completed. Few   
decisions are still needed, among them the most important is whether to   
stagger the boards (and fit 2 boards within 9mm thickness) or not to   
stagger them (having ~6-7mm per board thickness) and occupy more space.   
 From the discussion it seems that the 1st option is preferred. Jakub   
found nice Samtec connectors (4.5mm thickness) with 80 or 160 pins,   
which seem the best candidate for connection between sensor and front-end PCB.  
  
Hans presentation about modification of APV PCB to allow charge sharing   
is uploaded on the meeting page. Involved people, please read it and send comments!  
  
Discussion about the beam-test  
- for 2019 year FCAL has not got the test-beam time, but it is not   
excluded that we get few day at the end of the year  
- we are asking (Sergei will do it a.s.a.p.) for 2 weeks in February   
2020. We decided to ask for setup with both for telescope and magnet  
- for the best preparation of the test-beam, both mechanics and sensors   
should be send in advance to Krakow, so that we can verify and optimize   
multi-plane operation with FPGA-based FLAME readout. Disassembled setup   
would be then send to DESY  
  
Internal call for AIDA++ (AIDA-2020 successor) is open. Applications   
should be sent by 15 of July. Please find attached the guideline and   
template. Please think about, so that on the next HWG meeting (19th or   
26th of June) we will decide about the key points of our application, and shape&tune our proposal after the meeting. Please send me your proposals by 14th of June!!!. So that I'll put it together and resend to   
everybody before HWG meeting as the basis for discussion.  
by 14th June REMEMBER!!!  
  
  
Best Regards,  
   Marek